

PCN# 20180222002
Transfer of select VIP2 devices from GFAB to DFAB Wafer Fab site
Change Notification / Sample Request

Date: February 23, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20180222002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM6132BIN/NOPB	null
LM6144BIN/NOPB	null
LM6132AIM/NOPB	null
LM6132AIMX/NOPB	null
LM6132BIM/NOPB	null
LM6132BIMX/NOPB	null
LM6134AIM/NOPB	null
LM6134AIMX/NOPB	null
LM6134BIM/NOPB	null
LM6134BIMX/NOPB	null
LM6142AIM/NOPB	null
LM6142BIM/NOPB	null
LM6142BIMX/NOPB	null
LM6142BIN/NOPB	null
LM6144AIM/NOPB	null
LM6144BIM/NOPB	null
LM6152ACM/NOPB	null
LM6152ACMX/NOPB	null
LM6152BCM/NOPB	null
LM6154BCM/NOPB	null
LM6134BIN/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180222002	PCN Date:	Feb 23, 2018
Title:	Transfer of select VIP2 devices from GFAB to DFAB (DL-LIN) Wafer Fab site		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	May 23, 2018	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change

PCN Details

Description of Change:

This change notification is to announce the transfer of select VIP2 devices from GFAB to the DFAB (DL-LIN) Wafer Fab site for the selected devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	VIP2	150 mm	DL-LIN	VIP2	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

GFAB closure

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current:

Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock

New Fab Site:

New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DL-LIN	DLN	USA	Dallas

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483S12
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO:MLA (23L) ACO:MYS

Product Affected:

LM6132AIM	LM6134AIMX/NOPB	LM6142AIMX	LM6144BIMX/J7000532
LM6132AIM/NOPB	LM6134BIM	LM6142AIMX/NOPB	LM6144BIMX/NOPB
LM6132AIMX	LM6134BIM/NOPB	LM6142BIM	LM6144BIN/NOPB
LM6132AIMX/NOPB	LM6134BIMX/E7001806	LM6142BIM/NOPB	LM6152ACM
LM6132BIM	LM6134BIMX/E7002931	LM6142BIMX	LM6152ACM/NOPB

LM6132BIM/NOPB	LM6134BIMX/J7000531	LM6142BIMX/NOPB	LM6152ACMX
LM6132BIMX	LM6134BIMX/NOPB	LM6142BIN/NOPB	LM6152ACMX/NOPB
LM6132BIMX/NOPB	LM6134BIMX/S7002550	LM6144AIM	LM6152BCM/NOPB
LM6132BIMX/S7002551	LM6134BIMX/SL110237	LM6144AIM/NOPB	LM6152BCM/NOPB
LM6132BIMX/SL110236	LM6134BIN/NOPB	LM6144AIMX/NOPB	LM6154BCM
LM6132BIN/NOPB	LM6142 MWC	LM6144BIM	LM6154BCM/NOPB
LM6134AIM	LM6142AIM	LM6144BIM/NOPB	LM6154BCM/NOPB
LM6134AIM/NOPB	LM6142AIM/NOPB	LM6144BIMX	

Qualification Report

DFAB VIP2 Technology Qualification

Approve Date 21-Feb-2018

Product Attributes

Attributes	Qual Device: LM6142AIM/NOPB
Assembly Site	TIEMA
Package Family	SOIC
Flammability Rating	-
Wafer Fab Supplier	DFAB 200MM
Wafer Process	VIP2

- Qual Devices qualified at LEVEL1-260CG: LM6142AIM/NOPB

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM6142AIM/NOPB
AC	Autoclave 121C	96 Hours	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HBM	ESD - HBM	2500 V	3/9/0
CDM	ESD - CDM	1500 V	3/9/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
MQ	Manufacturability (Auto Assembly)	(per automotive requirements)	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass
PC	Pre-Conditioning	Level 1-260C	3/720/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com